

wherein the primary surface of said semiconductor element is bonded to the primary surface of said circuit board by means of an adhesive layer which is greater in size than the primary surface of said semiconductor element,

said adhesive layer extends outside an outer edge of the primary surface of said semiconductor element without reaching an outer edge of the primary surface of said circuit board,

said element electrode of said semiconductor element is connected to said board electrode provided on the back surface of said circuit board via said opening hole, and

said semiconductor element and said circuit board directly contact each other via the adhesive layer in order to relieve tension between said semiconductor element and said circuit board by the adhesive layer.

4. (Amended) The semiconductor device according to claim 1, wherein said adhesive layer extends radically outward relative to and completely around the primary surface of said semiconductor element.

SEE APPENDIX FOR CHANGES MADE TO THE CLAIMS.

### REMARKS

#### **I. REQUEST TO WITHDRAW FINALITY OF OUTSTANDING OFFICE ACTION**

It is respectfully submitted that the finality of the outstanding Office Action is premature because the Examiner has set forth a new ground of rejection that was NOT necessitated by amendment. In particular, the Examiner has newly relied on Miyazaki et al. (JP '535 submitted